



AAEON Technology INC.
ISO-9001/ISO-14001 Certified
Industrial Automation PCs

GENE-6310 Rev:B1.0

Thermal Image Analysis Report

VIA C3 Eden 733MHz CPU

Release Date: Aug. 29, 2003

08-29-2003
Issue Stamp

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Thermal Image Analysis

I . Model Name: GENE-6310 Rev.B1.0 (BIOS:B1.0)

II . Description: Low-power SubCompact Board.

III . Date: Aug. 28, 2003

IV. Measure Site: AAEON DV Dept.

V . Issued by : Rex Chang

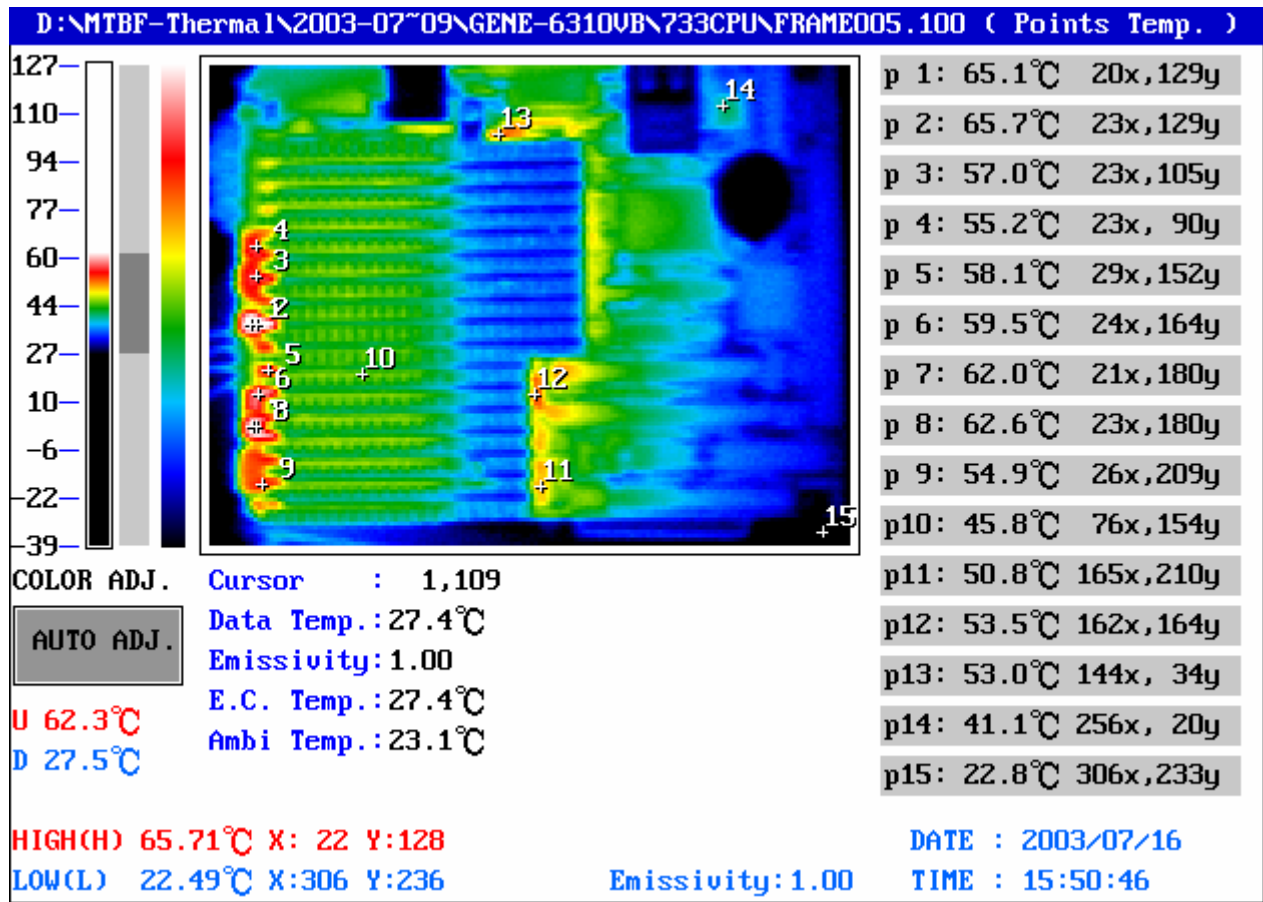
VI.Equipment : TVS-100 IR Thermal Tester

VII. Simulation Environment:

- **Temperature: 22.8 degrees C**
- **CPU: Onboard VIA C3 Eden 733MHz CPU**
- **RAM: KINGMAX KSV684T4A2C-07 256MB SODIMM (PC-133)**
- **HDD : Maxtor D540X-4G 160GB ATA/133**
- **Application Software: Windows XP / HCT9.5**
- **Take Picture Time: Power on 4 hours after**

Temperature Profile Test:

Component Side:



Picture 1

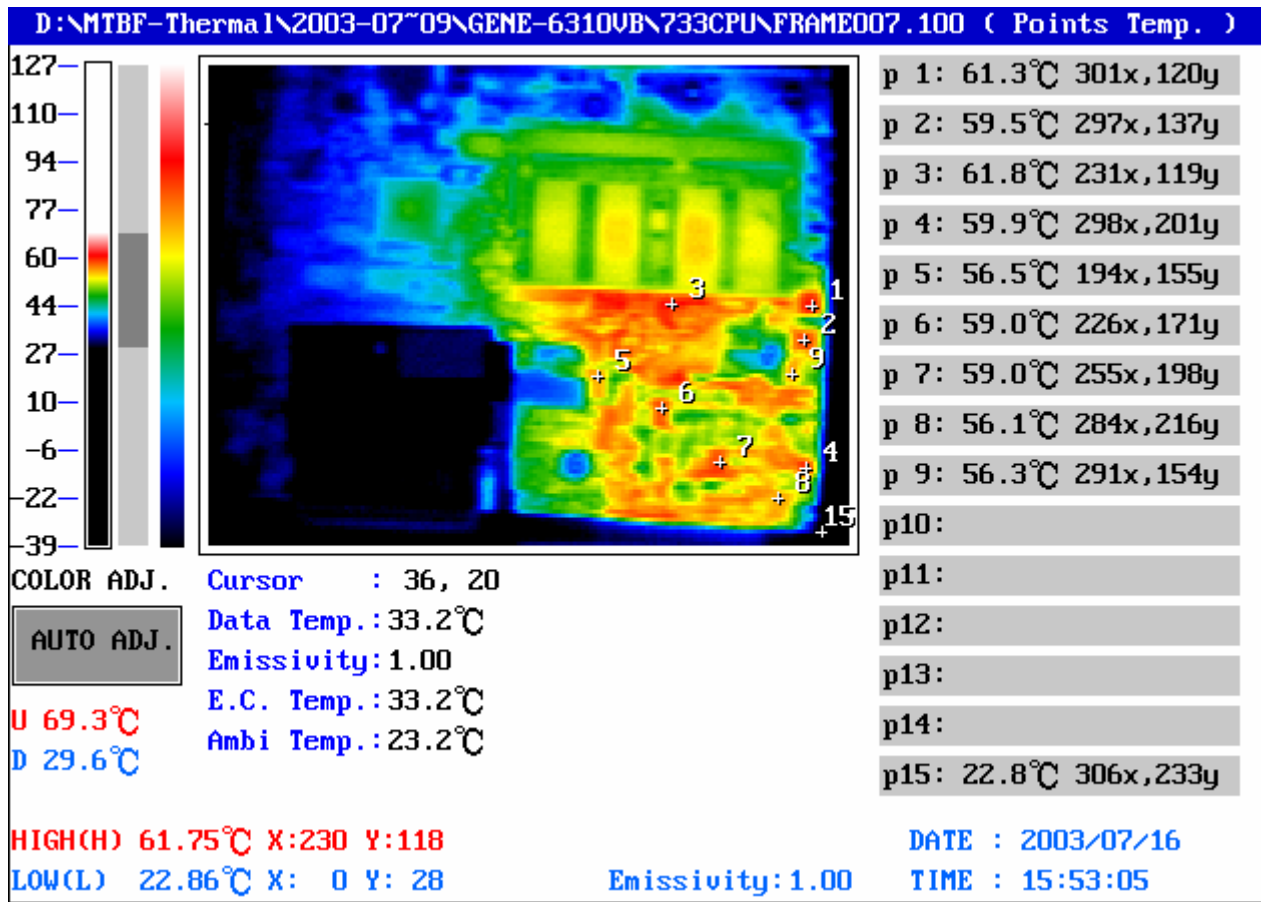
Point	Position	TVS-100 IR Thermal Tester
1	Q9	65.1°C
2	Q10	65.7°C
3	L66	57.0°C
4	C221	55.2°C
5	D12	58.1°C
6	C216	59.5°C
7	Q8	62.0°C
8	Q6	62.6°C
9	L65	54.9°C
10	U2/U12	45.8°C
11	U1	50.8°C
12	U3	53.5°C
13	U11	53.0°C
14	U14	41.1°C
15	The Room Temperature	22.8°C

1. Operation Temperature (°C):

Ts = Defined by component specification ; Tm = Measured by DV65

Temperature Profile Test:

Solder Side:



Picture 2

Point	Position	TVS-100 IR Thermal Tester
1	Q7	61.3°C
2	C137	59.5°C
3	U12	61.8°C
4	U27	59.9°C
5	C209	56.5°C
6	C93	59.0°C
7	C104	59.0°C
8	C215	56.1°C
9	D12	56.3°C
10		
11		
12		
13		
14		
15	The Room Temperature	22.8°C

1. Operation Temperature (°C):
Ts = Defined by component specification ; Tm = Measured by DV